

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Thorsten Meyer	08/12/2007
Harry Hedler	08/31/2007
Markus Brunnbauer	08/27/2007
RECEIVING PARTY DATA	
Name:	Infineon Technologies AG
Street Address:	Am Campeon 1-12
City:	Neubiberg
State/Country:	FEDERAL REPUBLIC GERMANY
Postal Code:	85579
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13195333
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ATTORNEY DOCKET NUMBER:	I446.118.102
NAME OF SUBMITTER:	Paul P. Kempf
Total Attachments: 2 source=ExecutedAssignment#page1.tif source=ExecutedAssignment#page2.tif	

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PATENT
REEL: 026680 FRAME: 0722

ASSIGNMENT

For good and valuable consideration, I, Thorsten Meyer, a citizen of Germany, residing at Altdorferstrasse 3A, 93049 Regensburg, Germany; Harry Hedler, a citizen of Germany, residing at Jahnstrasse 8, 82110 Germering, Germany; and Markus Brunnbauer, a citizen of Germany, residing at Regenstrasse 2, 93138 Lappersdorf, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation, organized and existing under the laws of Germany, having its principal place of business at Am Campcon 1-12, 85579 Neubiberg, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and was filed on July 12, 2007 as U.S. Application No. 11/776,976, entitled:

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and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and


Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

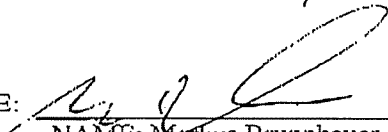
SIGNATURE: _____

NAME: Thorsten Meyer

DATE: _____

12.08.07

SIGNATURE:  DATE: 31.08.07
NAME: Harry Hedler

SIGNATURE:  DATE: 27.8.07
NAME: Markus Brunnbauer